


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

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| 1.1 Company |  STMicroelectronics International N.V |
| 1.2 PCN No. | EMBEDDED PROCESSING/25/15887 |
| 1.3 Title of PCN | TSHT(China) additional LQFP7x7 32L/48L package assembly line for STM32G07x/G08x and STM32G03x/04x listed products. |
| 1.4 Product Category | STM32G030x, STM32G031x, STM32G041x, STM32G070x, STM32G071x and STM32G081x. |
| 1.5 Issue date | 2025-10-07 |

2. PCN Team

| | |
|---------------------------|---------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | PIKE EMMA |
| 2.1.2 Phone | +44 1628896111 |
| 2.1.3 Email | emma.pike@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Patrick AIDOUNE |
| 2.1.2 Marketing Manager | Veronique BARLATIER |
| 2.1.3 Quality Manager | Pascal NARCHE |

3. Change

| | | |
|--------------|---|----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Transfer | Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617) | TSHT (China) |

4. Description of change

| | | |
|---|--|--|
| | Old | New |
| 4.1 Description | Current Wire bonding material: - JSCC (China) Gold wire or copper wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire | Current Wire bonding material: - JSCC (China) Gold wire or copper wire - ASE Kaohsiung (Taiwan) Gold wire or Copper Palladium wire Added Wire bonding material : - TSHT(China) Copper Palladium wire |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No change - no impact on form, Fit, Function | |

5. Reason / motivation for change

| | |
|----------------------|---|
| 5.1 Motivation | Due to the success on the market of STM32 devices, ST General Purpose Microcontroller sub-group decided to extend the capacity through an already qualified back-end site to maintain state of the art service level to our customers thanks to extra capacity. |
| 5.2 Customer Benefit | CAPACITY INCREASE |

6. Marking of parts / traceability of change

| | |
|-----------------|---|
| 6.1 Description | traceability ensured by ST internal tools |
|-----------------|---|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2026-01-05 |
| 7.2 Intended start of delivery | 2026-02-05 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|--|---|------------|------------|
| 8.1 Description | 15887 MDRF-GPAM-RER2501 for PCN15887 TSHT(China) additional listed products_ - Reliability plan.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2025-10-07 |

| 9. Attachments (additional documentations) | |
|--|--|
| 15887 Public product.pdf 15887 MDRF-GPAM-RER2501 for PCN15887 TSHT(China) additional listed products_ - Reliability plan.pdf 15887 _Additional information.pdf | |

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | STM32G070CBT6TR | |
| | STM32G070KBT6 | |
| | STM32G070KBT6TR | |

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